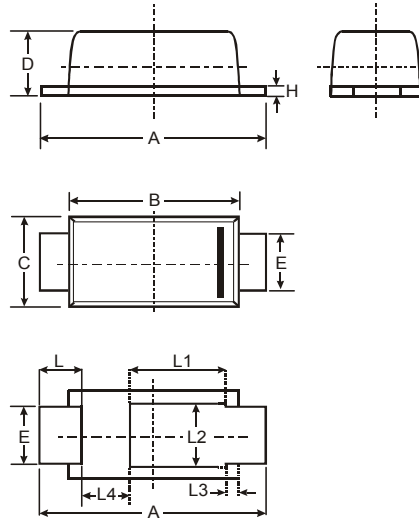


Features

- Guard Ring Die Construction for Transient Protection
- Low Power Loss, High Efficiency
- Patented Interlocking Clip Design for High Surge Current Capacity
- High Current Capability and Low Forward Voltage Drop
- **Lead Free Finish, RoHS Compliant (Note 4)**
- **"Green" Molding Compound (No Br, Sb)**
- **Qualified to AEC-Q101 Standards for High Reliability**



PowerDI™ 123			
Dim	Min	Max	Typ
A	3.65	3.75	3.70
B	2.775	2.825	2.80
C	1.750	1.800	1.775
D	0.955	1.000	0.98
E	0.95	1.05	1.00
H	0.15	0.25	0.20
L	0.60	0.70	0.65
L1	—	—	1.36
L2	—	—	1.10
L3	—	—	0.20
L4	0.95	1.25	1.05
All Dimensions in mm			

Mechanical Data

- Case: PowerDI™ 123
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020C
- Terminal Connections: Cathode Band
- Terminals: Finish – Matte Tin annealed over Copper leadframe. Solderable per MIL-STD-202, Method 208 (E3)
- Marking Information: See Page 3
- Ordering Information: See Page 3
- Weight: 0.096 grams (approximate)

Maximum Ratings @T_A = 25°C unless otherwise specified

Single phase, half wave, 60Hz, resistive or inductive load. For capacitive load, derate current by 20%.

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage	V _{RRM}	40	V
Working Peak Reverse Voltage	V _{RWM}		
DC Blocking Voltage	V _R		
RMS Reverse Voltage	V _{R(RMS)}	28	V
Average Forward Current @ T _T = 120°C	I _{F(AV)}	1.0	A
Non-Repetitive Peak Forward Surge Current 8.3ms single half sine-wave superimposed on rated load	I _{FSM}	50	A

Thermal Characteristics @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 1)	P _D	1.67	W
Power Dissipation (Note 2)	P _D	556	mW
Thermal Resistance Junction to Soldering Point (Note 3)	R _{θJS}	10	°C/W
Thermal Resistance Junction to Ambient (Note 1)	R _{θJA}	60	°C/W
Thermal Resistance Junction to Ambient (Note 2)	R _{θJA}	180	°C/W
Operating Temperature Range	T _j	-55 to +125	°C
Storage Temperature Range	T _{STG}	-55 to +150	°C

- Notes:
1. Part mounted on 50.8mm X 50.8mm GETEK board with 25.4mm X 25.4mm copper pad, 25% anode, 75% cathode. T_A = 25°C
 2. Part mounted on FR-4 board with 1.8mm X 2.5mm cathode and 1.8mm X 1.2mm anode, 1 oz. copper pads. T_A = 25°C
 3. Theoretical R_{θJS} calculated from the top center of the die straight down to the PCB cathode tab solder junction.
 4. RoHS revision 13.2.2003. High temperature solder exemption applied, see *EU Directive Annex Note 7*.

Electrical Characteristics @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 5)	V _{(BR)R}	40	—	—	V	I _R = 500μA
Forward Voltage	V _F	—	—	0.36	V	I _F = 0.1A, T _J = 25°C
		—	—	0.30		I _F = 0.1A, T _J = 85°C
		—	—	0.55		I _F = 1.0A, T _J = 25°C
		—	—	0.515		I _F = 1.0A, T _J = 85°C
		—	—	0.85		I _F = 3.0A, T _J = 25°C
		—	—	0.88		I _F = 3.0A, T _J = 85°C
Leakage Current (Note 5)	I _R	—	—	0.5	mA	V _R = 40V, T _J = 25°C
		—	—	25		V _R = 40V, T _J = 85°C
		—	—	0.15		V _R = 20V, T _J = 25°C
		—	—	18		V _R = 20V, T _J = 85°C
Total Capacitance	C _T	—	55	—	pF	V _R = 10V, f = 1.0MHz

Notes: 5. Short duration pulse test to minimize self-heating effect.

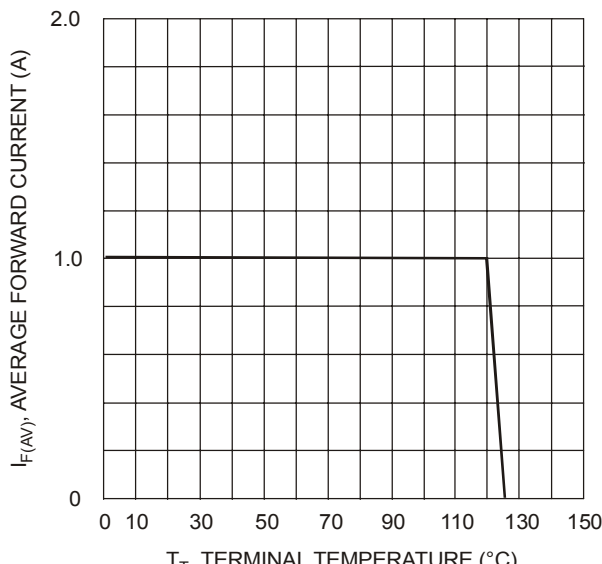


Fig. 1, Forward Current Derating Curve

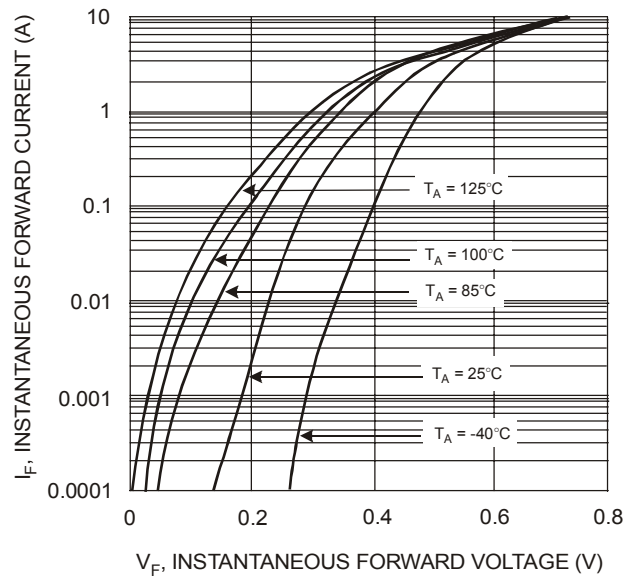


Fig. 2, Typical Forward Characteristics

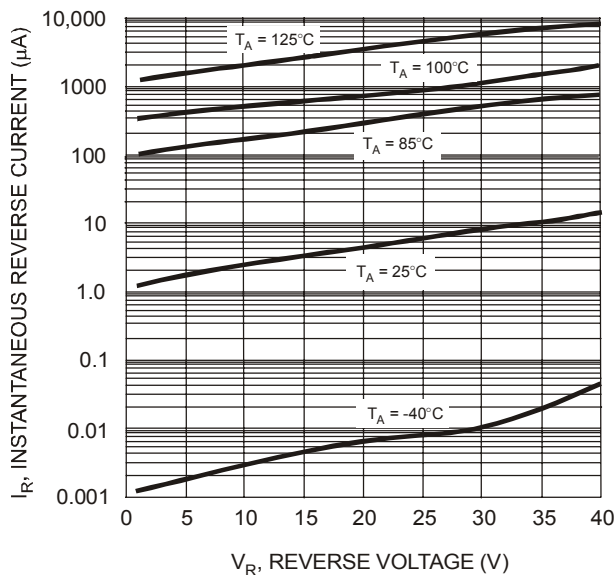


Fig. 3, Typical Pulsed Reverse Characteristics

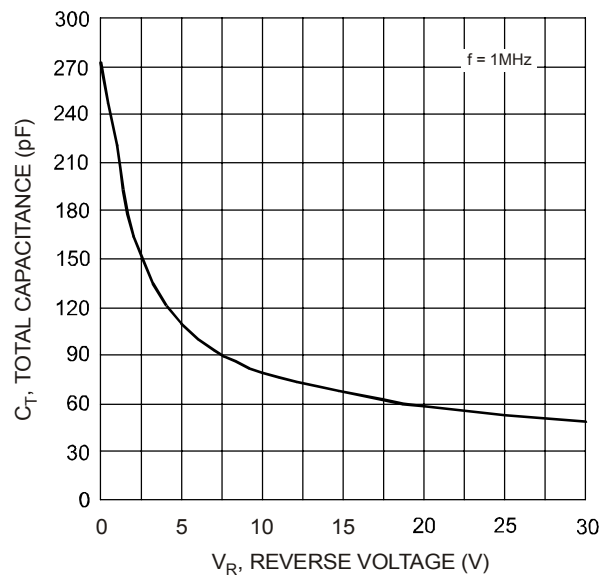


Fig. 4, Typical Total Capacitance vs Reverse Voltage

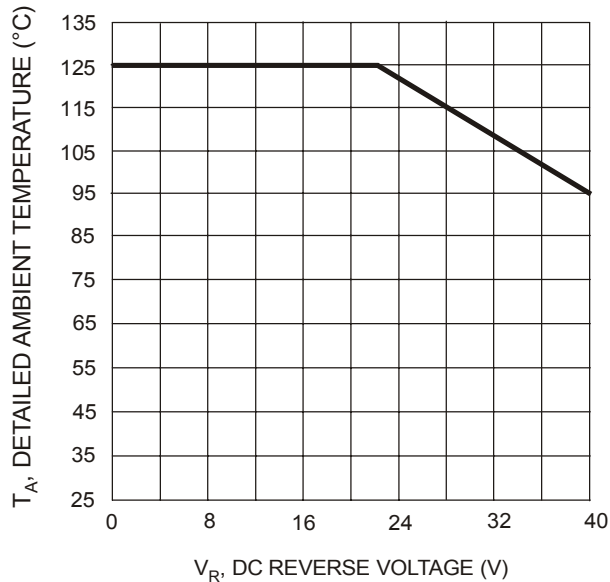


Fig. 5 Operating Temperature Derating

Ordering Information (Note 6)

Device	Packaging	Shipping
DFLS140L-7	PowerDI™123	3000/Tape & Reel

Notes: 6. For packaging details, go to our website at <http://www.diodes.com/datasheets/ap02007.pdf>.

Marking Information



F06 = Product Type Marking Code
 YM = Date Code Marking
 Y = Year (ex: T = 2006)
 M = Month (ex: 9 = September)

Date Code Key

Year	2004	2005	2006	2007	2008	2009	2010	2011	2012
Code	R	S	T	U	V	W	X	Y	Z

Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	O	N	D

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